Lattice Semiconductor Corporation - LC51024VG-75F484C Datasheet

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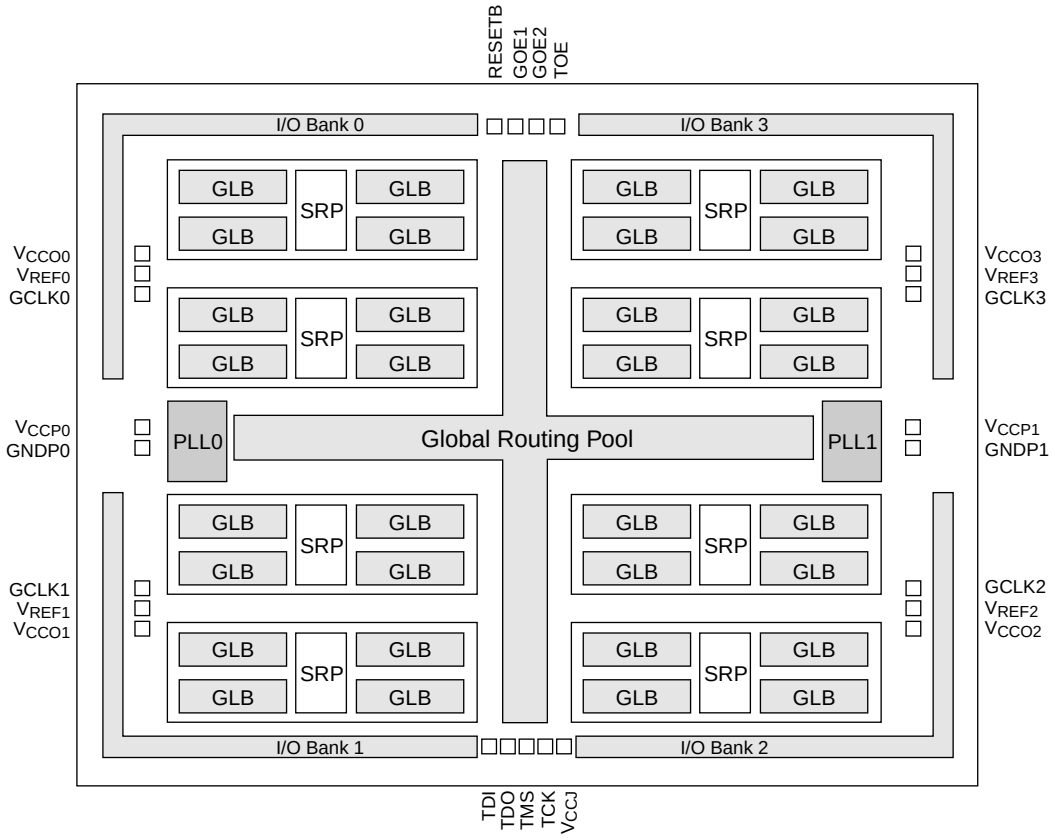
Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	1024
Number of Gates	-
Number of I/O	304
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc51024vg-75f484c

Figure 1. Functional Block Diagram



Overview

The ispMACH 5000VG devices consist of multiple SuperWIDE 68-input, 32-macrocell Generic Logic Blocks (GLBs) interconnected by a tiered routing system. Figure 1 shows the functional block diagram of the ispMACH 5000VG. Groups of four GLBs, referred to as segments, are interconnected via a Segment Routing Pool (SRP). Segments are interconnected via the Global Routing Pool (GRP.) Together the GLBs and the routing pools allow designers to create large designs in a single device without compromising performance.

Each GLB has 68 inputs coming from the SRP and contains 163 product terms. These product terms form groups of five product term clusters, which feed the PT sharing array or the macrocell directly. The ispMACH 5000VG allows up to 160 product terms to be connected to a single macrocell via the product term expanders and PT Sharing Array.

The macrocell is designed to provide flexible clocking and control functionality with the capability to select between global, product term and block-level resources. The outputs of the macrocells are fed back into the switch matrices and, if required, the sysIO cell.

All I/Os in the ispMACH 5000VG family are sysIOs, which are split into four banks. Each bank has a separate I/O power supply and reference voltage. The sysIO cells allow operation with a wide range of today's emerging interface standards. Within a bank, inputs can be set to a variety of standards, providing the reference voltage requirements of the chosen standards are compatible. Within a bank, the outputs can be set to differing standards, providing the I/O power supply voltage and the reference voltage requirements of the chosen standard are compatible. Support for this wide range of standards allows designers to achieve significantly higher board-level performance compared to the more traditional LVCMOS standards.

The ispMACH5000VG devices also contain sysCLOCK Phase Locked Loops (PLLs) that provide designers with increased clocking flexibility. The PLLs can be used to synthesize new clocks for use on-chip or elsewhere within the system. They can also be used to deskew clocks, again both at the chip and system levels. A variable delay line capability further improves this and allows designers to retard or advance the clock in order to tune set-up and clock-to-out times for optimal results. The ispMACH 5000VG Family Selection Guide (Table 1) details the key attributes and packages for the ispMACH 5000VG devices.

ispMACH 5000VG Architecture

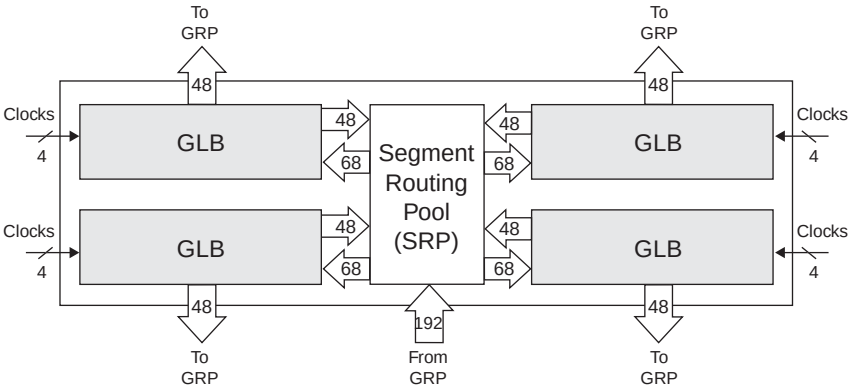
The ispMACH 5000VG Family of In-System Programmable High Density Logic Devices is based on segments containing four Generic Logic Blocks (GLBs) and a hierarchical routing pool (GRP) structure interconnecting the segments. A segment routing pool (SRP) connects each GLB in a segment allowing the maximum flexibility and speed.

Outputs from the GLBs drive the Segment Routing Pool (SRP) and the Global Routing Pool (GRP). Enhanced switching resources are provided to allow signals in the Segment Routing Pool to drive any or all the GLBs in the segment. Optimal switching is provided to allow all signals in the Global Routing Pool to be routed to any or all SRPs. This mechanism allows fast, efficient connections across the entire device.

Segment

Each segment contains four GLBs and a segment routing pool (SRP). Each GLB has 32 internal feedback outputs and 16 external feedback outputs, for a total of 48 outputs from each GLB feeding the SRP. The SRP contains up to 384 signals, 48 from each GLB and 192 from the GRP, with full routing capability. This routing scheme maximizes the flexibility and speed of the device without sacrificing the routing.

Figure 2. Segment



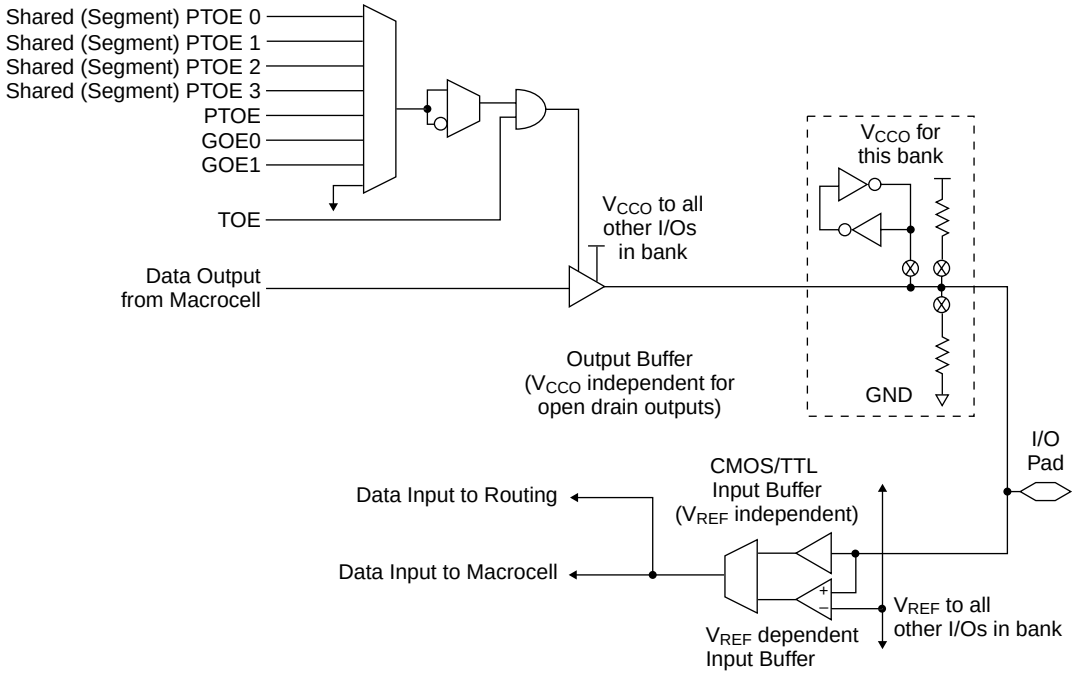
Generic Logic Block

Each GLB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and three control product terms. The GLB has 68 inputs from the Segment Routing Pool, which are available in both true and complement form for every product term. The three control product terms are used for shared reset, clock and output enable functions. Figure 3 shows the structure of the GLB from the macrocell perspective. This is referred to as a macrocell slice. There are 32 macrocell slices per GLB.

AND-Array

The programmable AND-Array consists of 68 inputs and 163 output product terms. The 68 inputs from the SRP are used to form 136 lines in the AND-Array (true and complement of the inputs). Each line in the array can be connected to any of the 163 output product terms via a wired AND. Each of the 160 logic product terms feed the Dual-OR Array with the remaining three control product terms feeding the Shared PT Clock, Shared PT Reset and Shared PT OE. Every set of five product terms from the 160 logic product terms forms a product term cluster start-

Figure 8. I/O Cell



sysIO Capability

The ispMACH 5000VG devices are divided into four sysIO banks, where each bank is capable of supporting 14 different I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCO}) and reference voltage (V_{REF}) resources allowing each bank complete independence from the others. Each I/O within a bank is individually configurable based on the V_{CCO} and V_{REF} settings. Table 2 lists the sysIO standards with the typical values for V_{CCO}, V_{REF} and V_{TT}.

Table 2. ispMACH 5000VG Supported I/O Standards

sysIO Standard	V_{CCO}	V_{REF}	V_{TT}
LVTTL	3.3V	N/A	N/A
LVCMOS-3.3	3.3V	N/A	N/A
LVCMOS-2.5	2.5V	N/A	N/A
LVCMOS-1.8	1.8V	N/A	N/A
PCI 3.3	3.3V	N/A	N/A
PCI-X	3.3V	N/A	N/A
AGP-1X	3.3V	N/A	N/A
SSTL3, Class I & II	3.3V	1.5V	1.5V
SSTL2, Class I & II	2.5V	1.25V	1.25V
CTT 3.3	3.3V	1.5V	1.5V
CTT 2.5	2.5V	1.25V	1.25V
HSTL, Class I	1.5V	0.75V	0.75V
HSTL, Class III	1.5V	0.9V	1.5V
GTL+	N/A	1.0V	1.5V
LVPECL, Differential[1]	N/A	N/A	N/A
LVDS[1]	N/A	N/A	N/A

1. LVDS and LVPECL are only supported on the dedicated clock pins.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 5000VG devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic notes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispMACH 5000VG family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

IEEE 1532-Compliant In-System Programming

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 5000VG devices provide In-System Programming (ISP™) capability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The ispMACH 5000VG devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 5000VG devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 5000VG devices during the testing of a circuit board.

Security Bit

A programmable security bit is provided on the ispMACH 5000VG devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary design from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Hot Socketing

The ispMACH 5000VG devices are well suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Density Migration

The ispMACH 5000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Absolute Maximum Ratings[1, 2, 3]

Supply Voltage (V_{CC}) . . . . . -0.5 to 5.4V

PLL Supply Voltage (V_{CCP}) . . . . . -0.5 to 5.4V

Output Supply Voltage (V_{CCO}) . . . . . -0.5 to 5.4V

Input Voltage Applied[4] . . . . . -0.5 to 5.6V

Tri-state Output Voltage Applied. . . . . -0.5 to 5.6V

Storage Temperature . . . . . -65 to 150°C

Junction Temperature (Tj) with Power Applied . . . . . -55 to 130°C

1. Stress above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. Overshoot and Undershoot of -2V to (V_{IH} (MAX)+2) volts is permitted for a duration of < 20ns.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage	3.0	3.6	V
V_{CCP}	Supply Voltage for PLL block	3.0	3.6	V
V_{CCJ}	Supply Voltage for IEEE1149.1 Test Access Port	1.65	3.6	V
Tj (Commercial)	Junction Commercial Operation	0	90	C
Tj (Industrial)	Junction Industrial Operation	-40	105	C

Note: V_{CCJ} must be set in appropriate range to be compatible with desired LVCMOS standard.

Erase Reprogram Specifications

Parameter	Min	Max	Units
Erase/Reprogram Cycle	1000	—	Cycles

Hot Socketing Characteristics[1,2,3]

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{DK}	Input or I/O Leakage Current	$0 \le V_{IN} \le V_{IH}$ (MAX)	—	—	+/-100	µA
		V_{IH} (MAX) $\le V_{IN} \le$ 5.5V	—	—	+/-100	µA

1. Insensitive to sequence of V_{CC} and V_{CCO}. However, assumes monotonic rise / fall rates for V_{CC} and V_{CCO}.
2. LVTTL, LVCMOS only
3. $0 < V_{CC} \le V_{CC}$ (MAX), $0 < V_{CCO} \le V_{CCO}$ (MAX)

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition		Min	Typ	Max	Units
I_{IL}, I_{IH}[1]	Input or I/O Leakage Current	$0V \le V_{IN} \le V_{IH}$ (MAX)		—	—	+/-10	µA
I_{PU}[2]	I/O Weak Pull-up Resistor Current	$0 \le V_{IN} \le 0.7\ V_{CCO}$	V_{CCO} = 3.3	-30	—	-150	µA
			V_{CCO} = 2.5	-20	—	-150	µA
			V_{CCO} = 1.8	-10	—	-150	µA
I_{PD}[2]	I/O Weak Pull-down Resistor Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)		30	—	150	µA
I_{BHLS}[2]	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)		30	—	—	µA
I_{BHHS}[2]	Bus Hold High Sustaining Current	$V_{IN} = 0.7\ V_{CCO}$	V_{CCO} = 3.3	-30	—	—	µA
			V_{CCO} = 2.5	-20	—	—	µA
			V_{CCO} = 1.8	-10	—	—	µA
I_{BHLO}[2]	Bus Hold Low Overdrive Current	$0V \le V_{IN} \le V_{IH}$ (MAX)		—	—	150	µA
I_{BHHO}[2]	Bus Hold High Overdrive Current	$0V \le V_{IN} \le V_{IH}$ (MAX)		—	—	-150	µA
I_{CC}[3, 4, 5]	Operating Power Supply Current	V_{CC} = 3.3V		—	380	—	mA
V_{BHT}	Bus Hold Trip Points			V_{IL} (MAX)	—	V_{IH} (MIN)	V
C_1	I/O Capacitance[3]	V_{CC} = 3.3V, V_{IO} = 0 to V_{IH} (MAX)		—	10	—	pf
		V_{CCO} = 3.3V, 2.5, 1.8, 1.5					
C_2	Clock Capacitance[3]	V_{CC} = 3.3V, V_{IO} = 0 to V_{IH} (MAX)		—	10	—	pf
		V_{CCO} = 3.3V, 2.5, 1.8, 1.5					
C_3	Global Input Capacitance[3]	V_{CC} = 3.3V, V_{IO} = 0 to V_{IH} (MAX)		—	10	—	pf
		V_{CCO} = 3.3V, 2.5, 1.8, 1.5					

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. Only available for LVCMOS and LVTTL standards.
3. T_A = 25°C, f = 1.0MHz.
4. Device configured with 16-bit counters.
5. I_{CC} varies with specific device configuration and operating frequency.

sysIO DC Electrical Characteristics

Over Recommended Operating Conditions

Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}[2] (mA)	I_{OH}[2] (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVCMOS 3.3[1]	-0.3	0.8	2.0	5.5	0.4	2.4	20	-20
LVCMOS 3.3	-0.3	0.8	2.0	5.5	0.4	2.4	16, 12 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	5.5	0.4	2.4	20	-20
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCO} - 0.4	16, 12, 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCO}$	$0.65V_{CCO}$	3.6	0.4	V_{CCO}-0.4	12, 8, 5.33, 4	-12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
PCI 3.3	-0.3	$0.3V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
PCI-X	-0.3	$0.35V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
AGP-1X	-0.3	$0.3V_{CCO}$	$0.5V_{CCO}$	3.6	$0.1V_{CCO}$	$0.9V_{CCO}$	1.5	-0.5
SSTL3 class I	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.7	V_{CCO}-1.1	8	-8
SSTL3 class II	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.5	V_{CCO}-0.9	16	-16
SSTL2 class I	-0.3	V_{REF}-0.18	V_{REF}+0.18	3.6	0.54	V_{CCO}-0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF}-0.18	V_{REF}+0.18	3.6	0.35	V_{CCO}-0.43	15.2	-15.2
CTT 3.3	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	V_{REF}-0.4	V_{REF}+0.4	8	-8
CTT 2.5	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	V_{REF}-0.4	V_{REF}+0.4	8	-8
HSTL class I	-0.3	V_{REF}-0.1	V_{REF}+0.1	3.6	0.4	V_{CCO}-0.4	8	-8
HSTL class III	-0.3	V_{REF}-0.1	V_{REF}+0.1	3.6	0.4	V_{CCO}-0.4	24	-8
GTL+	-0.3	V_{REF}-0.2	V_{REF}+0.2	3.6	0.6	n/a	36	n/a

1. Software default setting
2. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed 96mA.

sysIO Differential Input DC Electrical Characteristics and Operating Conditions

Symbol	Parameter	Test Conditions	Min	Max
V_{INP} . V_{INM}	LVDS Input voltage	—	0	2.4
V_{THD}	LVDS Differential input threshold	—	±100mV	—
V_{IL}	LVPECL Input Voltage Low	V_{CC} = 3.0 to 3.6V	V_{CC}-1.81	V_{CC}-1.48
		V_{CC} = 3.3V	1.49V	1.83V
V_{IH}	LVPECL Input Voltage High	V_{CC} = 3.0 to 3.6V	V_{CC}-1.17	V_{CC}-0.88
		V_{CC} = 3.3V	2.14V	2.42V

ispMACH 5768VG External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description[1,2,3]	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	Data propagation delay, 5-PT bypass	—	5.0	—	7.5	—	10.0	—	12.0	ns
t_{PD_PTSA}	Data propagation delay, intrasegment path	—	6.0	—	9.0	—	11.5	—	13.5	ns
t_{PD_GLOBAL}	Data propagation delay, intersegment path	—	6.5	—	9.75	—	13.0	—	16.0	ns
t_S	GLB register setup time before clock, 5-PT bypass	3.0	—	5.0	—	7.5	—	9.3	—	ns
t_{S_PTSA}	GLB register setup time before clock	3.0	—	6.0	—	8.5	—	10.0	—	ns
t_{SIR}	GLB register setup time before clock, input register path	2.8	—	3.0	—	4.0	—	5.0	—	ns
t_H	GLB register hold time before clock, 5-PT bypass	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	GLB register hold time before clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time before clock, input reg. path	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	4.4	—	5.0	—	6.0	—	7.0	ns
t_R	External reset pin to output delay	—	6.5	—	9.0	—	10.0	—	10.9	ns
t_{RW}	External reset pulse duration	4.0	—	6.0	—	8.0	—	9.5	—	ns
$t_{LPTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	9.75	—	11.5	—	13.4	ns
$t_{SPTOE/DIS}$	Input to output segment product term output enable/disable	—	8.0	—	11.25	—	17.5	—	20.4	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	6.2	—	7.5	—	8.85	—	10.0	ns
t_{CW}	Global clock width, high or low	1.6	—	2.75	—	3.6	—	4.3	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{WIR}	Input register clock width, high or low	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{SKEW}	Clock-to-out skew, block level	—	0.25	—	0.35	—	0.45	—	0.55	ns
	Clock-to-out skew, segment level	—	0.4	—	0.5	—	0.6	—	0.7	ns
f_{MAX}[4]	Clock frequency with internal feedback	178.6	—	117.0	—	87.0	—	73.0	—	MHz
f_{MAX} (Ext.)	Clock frequency with external feedback, $1/ (t_{S\_PTSA} + t_{CO})$	135.1	—	90.9	—	69.0	—	58.8	—	MHz
f_{MAX} (Tog.)	Clock frequency max Toggle	312.5	—	181.0	—	138.0	—	116.0	—	MHz

Timing v.1.20

1. Timing numbers are based on default LVCMOS 3.3 I/O Buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, assuming segment and global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using SRP feedback.

ispMACH 51024VG External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description[1,2,3]	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	Data propagation delay, 5-PT bypass	—	5.0	—	7.5	—	10.0	—	12.0	ns
t_{PD_PTSA}	Data propagation delay, intrasegment path	—	6.0	—	9.0	—	11.5	—	13.5	ns
t_{PD_GLOBAL}	Data propagation delay, intersegment path	—	6.5	—	9.75	—	13.0	—	16.0	ns
t_S	GLB register setup time before clock, 5-PT bypass	3.0	—	5.0	—	7.5	—	9.3	—	ns
t_{S_PTSA}	GLB register setup time before clock	3.0	—	6.0	—	8.5	—	10.0	—	ns
t_{SIR}	GLB register setup time before clock, input register path	2.8	—	3.0	—	4.0	—	5.0	—	ns
t_H	GLB register hold time before clock, 5-PT bypass	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	GLB register hold time before clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time before clock, input reg. path	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	4.4	—	5.0	—	6.0	—	7.0	ns
t_R	External reset pin to output delay	—	6.5	—	9.0	—	10.0	—	10.9	ns
t_{RW}	External reset pulse duration	4.0	—	6.0	—	8.0	—	9.5	—	ns
$t_{LPTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	9.75	—	11.5	—	13.4	ns
$t_{SPTOE/DIS}$	Input to output segment product term output enable/disable	—	8.0	—	11.25	—	17.5	—	20.4	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	6.2	—	7.5	—	8.85	—	10.0	ns
t_{CW}	Global clock width, high or low	1.6	—	2.75	—	3.6	—	4.3	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{WIR}	Input register clock width, high or low	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{SKEW}	Clock-to-out skew, block level	—	0.25	—	0.35	—	0.45	—	0.55	ns
	Clock-to-out skew, segment level	—	0.4	—	0.5	—	0.6	—	0.7	ns
f_{MAX}[4]	Clock frequency with internal feedback	178.6	—	117.0	—	87.0	—	73.0	—	MHz
f_{MAX} (Ext.)	Clock frequency with external feedback, $1/ (t_{S\_PTSA} + t_{CO})$	135.1	—	90.9	—	69.0	—	58.8	—	MHz
f_{MAX} (Tog.)	Clock frequency max Toggle	312.5	—	181.0	—	138.0	—	116.0	—	MHz

Timing v.1.10

1. Timing numbers are based on default LVCMOS 3.3 I/O Buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, assuming segment and global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using SRP feedback.

ispMACH 51024VG Internal Timing Parameters (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{CES}	Clock Enable Setup Time	2.60	—	3.90	—	5.05	—	5.95	—	ns
t_{CEH}	Clock Enable Hold Time	0.60	—	0.90	—	1.20	—	1.45	—	ns
t_{SL}	Latch Setup Time	2.80	—	4.20	—	5.50	—	6.60	—	ns
t_{SL_PT}	Latch Setup Time with PT Clock	2.80	—	4.20	—	5.50	—	6.60	—	ns
t_{HL}	Latch Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t_{GOi}	Latch Gate to Output/Feedback MUX Time	—	1.75	—	2.50	—	3.50	—	4.50	ns
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	2.40	—	3.50	—	4.00	—	4.50	ns
t_{SRi}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.75	—	1.00	—	1.25	—	1.50	ns
t_{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.00	—	1.50	—	2.00	—	2.50	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	3.10	—	4.65	—	6.00	—	7.00	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	3.00	—	4.50	—	6.00	—	7.00	ns
t_{BSR}	Block PT Set/Reset Delay	—	2.00	—	3.00	—	4.00	—	4.80	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	2.00	—	3.00	—	4.00	—	4.80	ns
t_{SPTOE}	Segment PT OE Delay	—	2.40	—	3.60	—	7.75	—	9.10	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.40	—	2.10	—	1.75	—	2.10	ns

Notes: Timing v.1.10

1. Internal Timing Parameters are not tested and are for reference only. Refer to Timing Model in this data sheet for further details.
2. t_{PLL_DELAY} is the unit increment by which the clock signal can be incremented. The PLL can adjust the clock signal by up to 3.5ns in either direction in units of 0.5ns for each step.

ispMACH 5768VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
HSTL_III_out	t_{BUF}, t_{EN}, t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF}, t_{EN}, t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

Note: Open drain timing is the same as corresponding LVCMOS timing. Timing v.1.20

ispMACH 51024VG Timing Adders

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{BLA}	t_{ROUTE}	GLB Loading Adder	—	0.0	—	0.0	—	0.0	—	0.0	ns
t_{EXP}	t_{PTSA}	PT Expander Adder	—	1.5	—	2.0	—	2.5	—	2.5	ns
t_{LP}	t_{ROUTE}	Low Power Adder	—	1.5	—	1.5	—	1.5	—	1.5	ns
t_{IOI} Input Adders											
LVCMOS18_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using LVCMOS1.8 standard	—	0.90	—	0.90	—	0.90	—	0.90	ns
LVCMOS25_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using LVCMOS2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
LVCMOS33_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using LVCMOS3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using LVTTL standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using PCI_X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using SSTL3_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL3_II_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using SSTL3_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_I_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using SSTL2_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_II_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using SSTL2_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
CTT33_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using CTT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using CTT2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
HSTL_I_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using HSTL_I standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
HSTL_III_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using HSTL_III standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
GTL+_in	t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}	Using GTL+ standard	—	1.50	—	1.50	—	1.50	—	1.50	ns

Note: Open drain timing is the same as corresponding LVCMOS timing. Timing v.1.10

ispMACH 51024VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
LVDS_in	t_{GCLK_IN}	Using LVDS standard	—	1.70	—	1.70	—	1.70	—	1.70	ns
LVPECL_in	t_{GCLK_IN}	Using LVPECL standard	—	2.10	—	2.10	—	2.10	—	2.10	ns
t_{IOO} Output Adders											
LVCMOS18_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 4mA Buffer	—	3.00	—	3.00	—	3.00	—	3.00	ns
LVCMOS18_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 5.33mA Buffer	—	2.50	—	2.50	—	2.50	—	2.50	ns
LVCMOS18_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 8mA Buffer	—	1.85	—	1.85	—	1.85	—	1.85	ns
LVCMOS18_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 12mA Buffer	—	1.35	—	1.35	—	1.35	—	1.35	ns
LVCMOS25_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVCMOS25_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVCMOS25_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 8mA Buffer	—	0.70	—	0.70	—	0.70	—	0.70	ns
LVCMOS25_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 12mA Buffer	—	0.50	—	0.50	—	0.50	—	0.50	ns
LVCMOS25_16mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 2.5V & 16mA Buffer	—	0.25	—	0.25	—	0.25	—	0.25	ns
LVCMOS33_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 4mA Buffer	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVCMOS33_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 5.33mA Buffer	—	1.25	—	1.25	—	1.25	—	1.25	ns
LVCMOS33_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 8mA Buffer	—	0.40	—	0.40	—	0.40	—	0.40	ns
LVCMOS33_12mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 12mA Buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVCMOS33_16mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 16mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVCMOS33_20mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 3.3V & 20mA Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	t_{BUF}, t_{EN}, t_{DIS}	Output configured as LVTTL Buffer	—	0.0	—	0.0	—	0.0	—	0.0	ns
Slow Slew	t_{BUF}, t_{EN}	Output configured for slow slew rate	—	1.50	—	1.50	—	1.50	—	1.50	ns
PCI_out	t_{BUF}, t_{EN}, t_{DIS}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_out	t_{BUF}, t_{EN}, t_{DIS}	Using PCI-X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_out	t_{BUF}, t_{EN}, t_{DIS}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL3_I standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
SSTL3_II_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL3_II standard	—	-0.35	—	-0.35	—	-0.35	—	-0.35	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

ispMACH 51024VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
SSTL2_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL2_I standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL2_II_out	t_{BUF}, t_{EN}, t_{DIS}	Using SSTL2_II standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
CTT33_out	t_{BUF}, t_{EN}, t_{DIS}	Using CCT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_out	t_{BUF}, t_{EN}, t_{DIS}	Using CCT2.5 standard	—	0.25	—	0.25	—	0.25	—	0.25	ns
HSTL_I_out	t_{BUF}, t_{EN}, t_{DIS}	Using HSTL_I standard	—	-0.30	—	-0.30	—	-0.30	—	-0.30	ns
HSTL_III_out	t_{BUF}, t_{EN}, t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF}, t_{EN}, t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

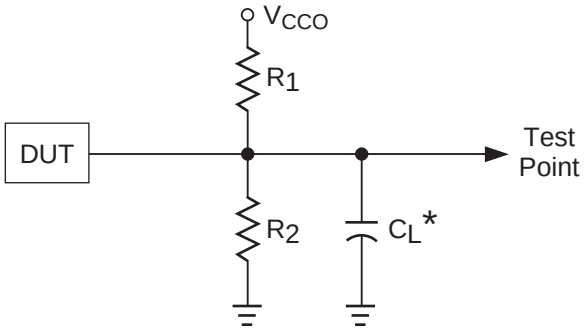
Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

Switching Test Conditions

Figure 12 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3.

Figure 12. Output Test Load, LVTTL and LVCMOS Standards



*C_L includes Test Fixture and Probe Capacitance.

0213A/ispm5kvg

Table 3. Test Fixture Required Components

Test Condition	R_1	R_2	C_L	Timing Ref.	V_{CCO}
Default LVCMOS 3.3 I/O (L -> H, H -> L)	110	110	35pF	1.5	3.0V
Other LVCMOS Settings, (L -> H, H -> L)	∞	∞	35pF	LVCMOS 3.3 = 1.5V	LVCMOS 3.3 = 3.0V
				LVCMOS 2.5 = V_{CCO}/2	LVCMOS 2.5 = 2.3V
				LVCMOS 1.8 = V_{CCO}/2	LVCMOS 1.8 = 1.65V
Default LVCMOS 3.3 I/O (Z -> H)	∞	110	35pF	1.5V	3.0V
Default LVCMOS 3.3 I/O (Z -> L)	110	∞	35pF	1.5V	3.0V
Default LVCMOS 3.3 I/O (H -> Z)	∞	110	5pF	V_{OH} - 0.3	3.0V
Default LVCMOS 3.3 I/O (L -> Z)	110	∞	5pF	V_{OL} + 0.3	3.0V

Output test conditions for all other interfaces are determined by the respective standards. For further details, please refer to the following technical note:

- *ispMACH 5000VG sysIO Design and Usage Guidelines* (TN1000)

ispMACH 5768VG Power Supply and NC Connections[1]

Signal	256-Ball fpBGA[2]	484-Ball fpBGA[2]
V_{CC}	F8, F9, H6, H11, J6, J11, L8, L9	B17, B2, B21, B6, C14, C9, E18, E5, F2, F21, J20, J3, P20, P3, U2, U21, Y14, Y9, AA17, AA2, AA21, AA6
V_{CCO0}	C3, C7, G3	B5, D7, E2, E6, E9, F5, G4, J5
V_{CCO1}	K3, P3, P7	P5, U5, V6, V9, Y3
V_{CCO2}	K14, P10, P14	P18, U18, V14, V17, Y20
V_{CCO3}	C10, C14, G14	B18, D16, E14, E17, E21, F18, G19, J18
V_{CCP0}	H1	L7
V_{CCP1}	H16	N18
V_{CCJ}	J1	P4
V_{REF0}	E7	A9
V_{REF1}	M7	AA10
V_{REF2}	R13	AA13
V_{REF3}	A8	A15
GND PLL 0	H7	L6
GND PLL 1	J10	L16
GND	A1, C5, C12, E3, E14, G7, G8, G9, G10, H8, H9, H10, J7, J8, J9, K7, K8, K9, K10, M3, M14, P5, P12	A1, A22, C3, C20, D4, D19, E7, E16, G5, G7, G8, G9, G10, G11, G12, G13, G14, G15, G16, G18, H7, H8, H9, H10, H11, H12, H13, H14, H15, H16, J7, J8, J9, J10, J11, J12, J13, J14, J15, J16, K7, K8, K9, K10, K11, K12, K13, K14, K15, K16, L8, L9, L10, L11, L12, L13, L14, L15, M7, M8, M9, M10, M11, M12, M13, M14, M15, M16, N7, N8, N9, N10, N11, N12, N13, N14, N15, N16, P7, P8, P9, P10, P11, P12, P13, P14, P15, P16, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, T4, T7, T8, T9, T10, T11, T12, T13, T14, T15, T16, T19, W7, W16, AB1, AB22
NC[3]	—	AA1

1. All grounds must be electrically connected at the board level.
2. Not all grounds internally connected within the device.
3. NC pins are not to be connected to any active signals, VCC or GND.

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
3	5C-20	C9	A13
3	5C-22	E9	B12
3	5C-24	D9	C13
3	5C-26	B8	A12
3	5C-28	A6	C12
3	5C-30	B7	A11
—	GCLK0	H4	P6
—	GCLK1	J4	R6
—	GCLK2	H14	P17
—	GCLK3	H13	P19
—	GOE0	J15	R18
—	GOE1	H15	R17
—	RESETB	J14	R19
—	TCK	J3	R3
—	TDI	H3	R2
—	TDO	J2	R4
—	TMS	H2	T1
—	TOE	J13	T18

ispMACH 51024VG Logic Signal Connections

Bank No.	Signal	484 fpBGA	676 fpBGA
0	0C-30	D11	A13
0	0C-28	B11	B13
0	0C-26	E12	A12
0	0C-24	C11	B12
0	0C-22	F12	C12
0	0C-20	B10	A11
0	GNDIO0	GND	GND
0	0C-18	A10	B11
0	0C-16	D10	A10
0	0C-14/VREF0	A9	C11
0	0C-12	E11	E12
0	0C-10	B9	B10
0	0C-8	F11	D11
0	0C-6	A8	A9
0	0C-4	C10	C10
0	0C-2	A7	B9
0	0C-0	E10	A8
0	0D-30	B8	C9
0	0D-28	C8	B8
0	GNDIO0	GND	GND
0	0D-26	F10	E10
0	0D-24	A6	A7
0	0D-22	F9	D9
0	0D-20	C7	C8
0	0D-18	D9	B7
0	0D-16	B7	A6
0	0D-14	E8	C7
0	0D-12	A5	B6
0	0D-10	F8	A5
0	0D-8	C6	C6
0	0D-6	D8	D7
0	0D-4	A3	E8
0	GNDIO0	GND	GND
0	0D-2	A2	B5
0	0D-0	A4	A4
0	0A-0	F7	A3
0	0A-2	C5	B4
0	0A-4	F6	C5
0	0A-6	B3	F8
0	0A-8	NC	A2
0	0A-10	NC	B3
0	GNDIO0	GND	GND
0	0A-12	NC	C4

Bank No.	Signal	484 fpBGA	676 fpBGA
0	0A-14	NC	D5
0	0A-16	B4	E6
0	0A-18	D5	D4
0	0A-20	B1	B1
0	0A-22	D6	C2
0	0A-24	C4	F6
0	0A-26	E4	D3
0	GNDIO0	GND	GND
0	0A-28	C2	E4
0	0A-30	C1	F5
0	0B-30	D1	C1
0	0B-28	D2	D2
0	0B-26	D3	E3
0	0B-24	E1	D1
0	0B-22	E3	E2
0	0B-20	F4	H6
0	0B-18	F1	F3
0	0B-16	F3	E1
0	0B-14	G6	G4
0	0B-12	G1	F2
0	GNDIO0	GND	GND
0	0B-10	G2	H5
0	0B-8	H1	G3
0	0B-6	G3	F1
0	0B-4	H2	G2
0	0B-2	H5	H3
0	0B-0	H6	G1
0	1A-0	J1	H2
0	1A-2	K1	J4
0	1A-4	H3	H1
0	1A-6	J2	J3
0	1A-8	H4	K5
0	1A-10	K2	J2
0	GNDIO0	GND	GND
0	1A-12	J6	J1
0	1A-14	L1	K3
0	1A-16	K3	K2
0	1A-18	J4	K1
0	1A-20	L2	L4
0	1A-22	M1	L3
0	1A-24	K6	L2
0	1A-26	K4	M5
0	1A-28	L3	L1

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
0	1A-30	K5	M3
0	GNDIO0	GND	GND
0	1B-30/CLK_OUT0	N1	M2
0	1B-28	M2	M1
0	1B-26	P1	N6
0	1B-24	L4	N5
0	1B-22	N2	N4
0	1B-20	M3	N3
0	1B-18	L5	N2
0	1B-16	R1	N1
0	1B-14	P2	P6
0	1B-12	N3	P4
0	GNDIO0	GND	GND
0	1B-10	M6	P3
0	1B-8	M5	P2
0	1B-6/PLL_RST0	M4	P1
0	1B-4/PLL_FBK0	N4	R4
0	1B-2	N6	R3
0	1B-0	N5	R2
1	2B-0	NC	R1
1	2B-2	NC	T1
1	2B-4	NC	T3
1	2B-6	NC	T2
1	2B-8	NC	U1
1	2B-10	NC	U2
1	GNDIO1	GND	GND
1	2B-12	NC	U3
1	2B-14	NC	U4
1	2B-16	NC	V1
1	2B-18	NC	V2
1	2B-20	NC	V3
1	2B-22	NC	V4
1	2B-24	NC	W1
1	2B-26	NC	V6
1	2B-28	NC	W2
1	2B-30	NC	W3
1	GNDIO1	GND	GND
1	2A-30	NC	Y1
1	2A-28	NC	W5
1	2A-26	NC	Y2
1	2A-24	NC	Y3
1	2A-22	NC	AA1
1	2A-20	NC	Y4

Bank No.	Signal	484 fpBGA	676 fpBGA
1	2A-18	NC	AA2
1	2A-16	NC	AA3
1	2A-14	NC	AB1
1	2A-12	NC	AB2
1	GNDIO1	GND	GND
1	2A-10	NC	AA5
1	2A-8	NC	AB3
1	2A-6	NC	AC1
1	2A-4	NC	AB4
1	2A-2	NC	AC2
1	2A-0	NC	AD1
1	3B-0	R5	AC3
1	3B-2	T2	AD2
1	3B-4	T5	AE1
1	3B-6	T3	AD3
1	3B-8	U1	AE2
1	3B-10	U4	AC5
1	GNDIO1	GND	GND
1	3B-12	V1	AF1
1	3B-14	U3	AD4
1	3B-16	V5	AE3
1	3B-18	V2	AC6
1	3B-20	W1	AF2
1	3B-22	V3	AG1
1	3B-24	W2	AF3
1	3B-26	Y1	AG2
1	3B-28	Y2	AH1
1	3B-30	W3	AE5
1	3A-30	AA3	AF4
1	3A-28	W4	AG3
1	GNDIO1	GND	GND
1	3A-26	W5	AE6
1	3A-24	Y4	AH2
1	3A-22	T6	AJ1
1	3A-20	Y5	AG4
1	3A-18	U6	AF6
1	3A-16	AA4	AG5
1	3A-14	NC	AH4
1	3A-12	NC	AJ3
1	GNDIO1	GND	GND
1	3A-10	NC	AK2
1	3A-8	NC	AE8
1	3A-6	W6	AH5

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
1	3A-4	V4	AJ4
1	3A-2	U7	AK3
1	3A-0	AB2	AK4
1	3D-0	V7	AJ5
1	3D-2	AA5	AH6
1	GNDIO1	GND	GND
1	3D-4	AB3	AF8
1	3D-6	Y6	AG7
1	3D-8	AB4	AK5
1	3D-10	Y7	AJ6
1	3D-12	AB5	AH7
1	3D-14	V8	AK6
1	3D-16	AA7	AJ7
1	3D-18	Y8	AH8
1	3D-20	AB6	AG9
1	3D-22	W8	AK7
1	3D-24	AA8	AF10
1	3D-26	Y10	AJ8
1	GNDIO1	GND	GND
1	3D-28	U8	AH9
1	3D-30	AB7	AK8
1	3C-0	U9	AJ9
1	3C-2	AA9	AH10
1	3C-4	W9	AK9
1	3C-6	AB8	AG11
1	3C-8	U10	AJ10
1	3C-10	AB9	AF12
1	3C-12	V11	AH11
1	3C-14/VREF1	AA10	AK10
1	3C-16	V10	AJ11
1	3C-18	AB10	AK11
1	GNDIO1	GND	GND
1	3C-20	W10	AH12
1	3C-22	W11	AJ12
1	3C-24	U11	AK12
1	3C-26	AA11	AH13
1	3C-28	V12	AJ13
1	3C-30	AB11	AK13
2	4C-30	W12	AK18
2	4C-28	Y11	AK19
2	4C-26	Y12	AJ19
2	4C-24	AB12	AH19
2	4C-22	U12	AK20

Bank No.	Signal	484 fpBGA	676 fpBGA
2	4C-20	AA12	AJ20
2	GNDIO2	GND	GND
2	4C-18	Y13	AK21
2	4C-16	AB13	AH20
2	4C-14	W13	AF19
2	4C-12/VREF2	AA13	AJ21
2	4C-10	U13	AG20
2	4C-8	AB14	AK22
2	4C-6	V13	AH21
2	4C-4	AA14	AJ22
2	4C-2	U14	AK23
2	4C-0	AB15	AH22
2	4D-30	Y15	AJ23
2	4D-28	AB16	AK24
2	GNDIO2	GND	GND
2	4D-26	AA15	AF21
2	4D-24	W14	AG22
2	4D-22	AB17	AH23
2	4D-20	Y16	AJ24
2	4D-18	AA16	AK25
2	4D-16	Y17	AH24
2	4D-14	AB18	AJ25
2	4D-12	V15	AK26
2	4D-10	AB19	AJ26
2	4D-8	W15	AH25
2	4D-6	AB20	AG24
2	4D-4	AA18	AF23
2	GNDIO2	GND	GND
2	4D-2	U15	AK27
2	4D-0	W17	AK28
2	4A-0	U16	AJ27
2	4A-2	AA19	AH26
2	4A-4	V16	AE23
2	4A-6	AB21	AK29
2	4A-8	NC	AJ28
2	4A-10	NC	AH27
2	GNDIO2	GND	GND
2	4A-12	NC	AG26
2	4A-14	NC	AF25
2	4A-16	Y18	AJ29
2	4A-18	W18	AG27
2	4A-20	AA20	AJ30
2	4A-22	W19	AH29

Signal Configuration

ispMACH 5768VG 256-ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O/ VREF3	I/O	I/O	I/O	I/O	I/O	I/O	GND	A
B	I/O	I/O	I/O	I/O	I/O	I/O/ CLK_OUT1	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	B
C	I/O	I/O	VCCO3	I/O	GND	I/O	VCCO3	I/O	I/O	VCCO0	I/O	GND	I/O	VCCO0	I/O	I/O	C
D	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	D
E	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O/ VREF0	I/O	I/O	I/O	GND	I/O	I/O	E
F	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC	VCC	I/O	I/O	I/O	I/O	I/O	I/O	I/O/ PLL_RST0	F
G	I/O	I/O/ PLL_FBK1	VCCO3	I/O	I/O	I/O	GND	GND	GND	GND	I/O/ CLK_OUT0	I/O	I/O	VCCO0	I/O/ PLL_FBK0	I/O	G
H	VCCP1	GOE1	GCLK2	GCLK3	I/O/ PLL_RST1	VCC	GND	GND	GND	GNDP0	VCC	I/O	GCLK0	TDI	TMS	VCCP0	H
J	I/O	GOE0	RESETB	TOE	I/O	VCC	GNDP1	GND	GND	GND	VCC	I/O	GCLK1	TCK	TDO	VCCJ	J
K	I/O	I/O	VCCO2	I/O	I/O	I/O	GND	GND	GND	GND	I/O	I/O	I/O	VCCO1	I/O	I/O	K
L	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC	VCC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	L
M	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O/ VREF1	I/O	I/O	I/O	GND	I/O	I/O	M
N	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	N
P	I/O	I/O	VCCO2	I/O	GND	I/O	VCCO2	I/O	I/O	VCCO1	I/O	GND	I/O	VCCO1	I/O	I/O	P
R	I/O	I/O	I/O	I/O/ VREF2	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	R
T	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	T
	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

ispMACH 5768VG

256fpBGA/5768VG

Bottom View

Note: Ball A1 indicator dot on top side of package.